

Part Number: Applicable to ASL-series.
Product Name: GaAs Amplifier
Package Type: UQFN6

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	0.0804	100
Leadframe	Cu	7440-50-8	0.474436	94.98
	Ni	7440-02-0	0.01959	3.92
	Si	7440-21-3	0.00345	0.69
	Mg	7439-95-4	0.000833	0.17
	Pd	7440-02-0	0.001019	0.2
	Au	7440-57-5	0.47444	0.03
Epoxy Molding Compound	Silica Fused	60676-86-0	0.579695	85.3
	Epoxy Resin 1	-	0.0238	3.5
	Epoxy Resin 2	-	0.0136	2
	Hardener 1	-	0.0238	4
	Metal hydroxide	-	0.0374	5.5
	Carbon Black	1333-86-4	0.00136	0.2
Epoxy Resin	Silver	7440-22-4	0.0256	80.0
	Epoxy resin	-	0.00448	14.0
	Dicyandiamide	461-58-5	0.00096	3.0
	Polymeric material	-	0.00096	3.0
Gold Wire	Au	7440-57-5	0.07283	100
Total			1.839	

This information sheet is to declare all substances intentionally added in our UQFN6 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which **COMPLY with the RoHS3 Directive 2015/863/EU**. For further information, contact our Sales Department at sales@asb.co.kr.



Authorized Signature, ASB Inc.

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